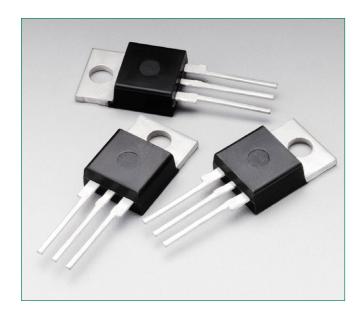


MCR8NG





Description

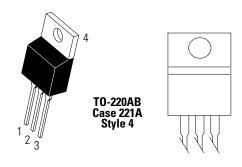
Designed primarily for half-wave ac control applications, such as motor controls, heating controls, and power supplies; or wherever half-wave, silicon gate-controlled devices are needed.

Features

- Blocking Voltage of 600 thru 800 Volts
- On-State Current Rating of 8 Amperes RMS at 80°C
- High Surge Current Capability – 80 Amperes
- Rugged, Economical TO-220AB Package
- Glass Passivated Junctions for Reliability and Uniformity
- Minimum and Maximum Values of IGT, VGT and IH Specified for Ease of Design
- High Immunity to dv/dt

 100 V/sec Minimum at
 125°C
- These are Pb–Free Devices

Pin Out



Functional Diagram



Additional Information







Samples

Thyristors Surface Mount – 600V - 800V > MCR8NG

 P_{GM}

P_{GM (AV)}

 I_{GM}

5.0

0.5

2.0

W

W

Α

Maximum Ratings $(T_1 = 25^{\circ}C \text{ unless otherwise noted})$ Rating **Symbol** Value Unit V_{DRM}, V_{RRM} Peak Repetitive Off-State Voltage (Note 1) MCR8MG 600 ٧ (- 40 to 1125°C, Sine Wave, 50 to 60 Hz, Gate Open) MCR8NG 800 On-State RMS Current (180° Conduction Angles; T_c = 80°C) T (RMS) 8.0 Α Peak Non-Repetitive Surge Current Α 80 I_{TSM} (One Full Cycle, 60 Hz, $T_c = 125$ °C) Circuit Fusing Consideration (t = 8.3 ms) l2t 26.5 A²sec

Operating Junction Temperature Range T_J -40 to +125 °C

Storage Temperature Range T_{stg} -40 to +150 °C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Thermal Characteristics

Forward Peak Gate Power (Pulse Width $\leq 1.0 \mu s$, $T_c = 80^{\circ}C$)

Forward Peak Gate Current (Pulse Width \leq 1.0 $\mu s,\,T_{_{\rm C}}$ = 80°C)

Forward Average Gate Power (t = 8.3 ms, $T_c = 80^{\circ}\text{C}$)

Rating		Symbol	Value	Unit
Thermal Resistance	R _{ejc} R _{eja}	2.2 62.5	°C/W	
Maximum Lead Temperature for Soldering Purp 10 seconds	T _L	260	°C	

Electrical Characteristics - **OFF** (T_c = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
†Peak Repetitive Blocking Current	T, = 25°C	I _{DRM} ,	-	-	0.01	μΑ
$(V_{AK} = V_{DRM} = V_{RRM}; Gate Open)$	T _J = 125°C	IRRM	-	-	2.0	mA

Electrical Characteristics - ON (T₁ = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Min	Тур	Max	Unit
Peak On-State Voltage (I _{TM} = 16 A)	V _{TM}	-	-	1.8	V
Gate Trigger Current (Continuous dc) ($V_D = 12 \text{ V}, R_L = 100 \Omega$)	I _{GT}	2.0	7.0	15	mA
Gate Trigger Voltage (Continuous dc) ($V_D = 12 \text{ V}, R_L = 100 \Omega$)		0.5	0.65	1.0	V
Gate Non-Trigger Voltage ($V_D = 12 \text{ V}, T_J = 125^{\circ}\text{C}, R_L = 100 \Omega$)	V _{GD}	0.2	_	_	V
Holding Current ($V_D = 12 \text{ V}$, Gate Open, Initiating Current = 200 mA)	I _H	4.0	17	30	mA
Latch Current $(V_D = 12 \text{ V}, I_G = 15 \text{ mA})$	IL	6.0	20	40	mA



Dynamic Characteristics

Characteristic	Symbol	Min	Тур	Max	Unit
Critical Rate of Rise of Off–State Voltage (V_D = Rated $V_{DRM'}$ Exponential Waveform, Gate Open, T_J = 125°C)	dv/dt	100	250	_	V/µs
Critical Rate of Rise of On–State Current (IPK = 50 A, Pw = 40 sec, diG/dt = 1 A/sec, lgt = 50 mA	di/dt	_	-	50	A/ms

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Indicates Pulse Test: Pulse Width :;; 2.0 ms, Duty Cycle :;; 2%.

Voltage Current Characteristic of SCR

Symbol	Parameter			
V_{DRM}	Peak Repetitive Forward Off State Voltage			
I _{DRM}	Peak Forward Blocking Current			
$V_{_{\rm RRM}}$	Peak Repetitive Reverse Off State Voltage			
IRRM	Peak Reverse Blocking Current			
V _{TM}	Maximum On State Voltage			
I _H	Holding Current			

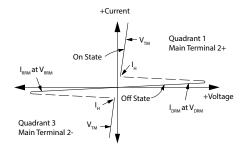


Figure 1. Typical RMS Current Derating

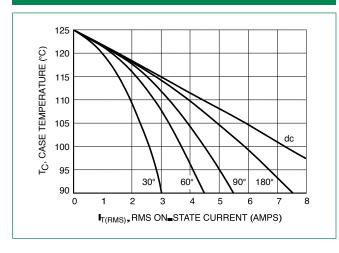


Figure 2. On-State Power Dissipation

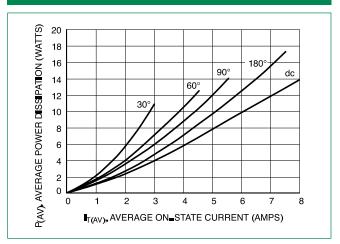




Figure 3. Typical On-State Characteristics

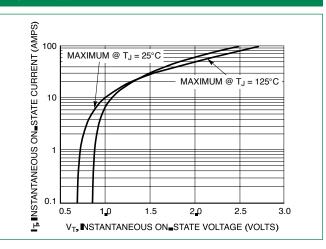


Figure 4. Typical Gate Trigger Current vs Junction Temperature

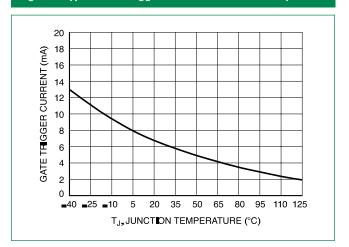


Figure 5. Typical Holding Current vs Junction Temperature

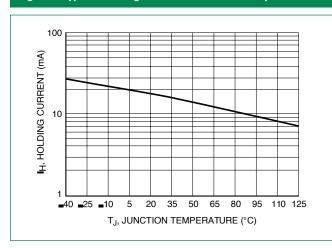


Figure 6. Typical Gate Trigger Voltage vs Junction Temperature

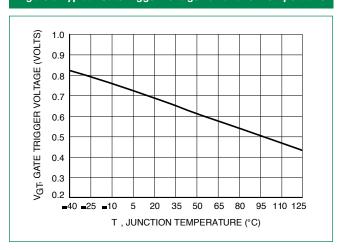
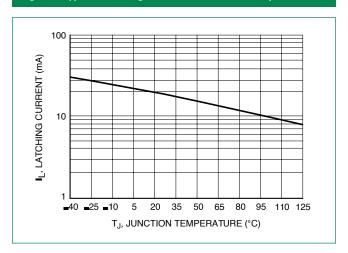
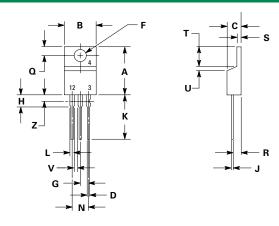


Figure 7. Typical Latching Current vs Junction Temperature

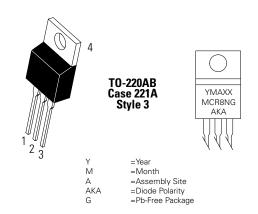




Dimensions



Part Marking System



D.	Inc	Inches Milli		meters	
Dim	Min	Max	Min	Max	
Α	0.590	0.620	14.99	15.75	
В	0.380	0.420	9.65	10.67	
С	0.178	0.188	4.52	4.78	
D	0.025	0.035	0.64	0.89	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.41	2.67	
Н	0.110	0.130	2.79	3.30	
J	0.018	0.024	0.46	0.61	
K	0.540	0.575	13.72	14.61	
L	0.060	0.075	1.52	1.91	
N	0.195	0.205	4.95	5.21	
Q	0.105	0.115	2.67	2.92	
R	0.085	0.095	2.16	2.41	
S	0.045	0.060	1.14	1.52	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Z		0.080		2.04	

Pin Assignment			
1	Cathode		
2	Anode		
3	Gate		
4	Anode		

Ordering Information					
Device	Package	Shipping			
MCR8NG	TO-220AB (Pb-Free)	500 Units/ Box			
MAC3030-8G	TO-220AB (Pb-Free)	500 Units/ Box			

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE